



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## SP0502B Series 1pF 15kV Diode Arrays

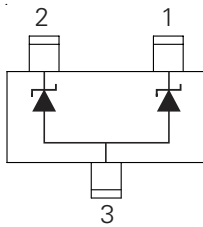


### Description

The SP0502B is a low capacitance TVS diode array designed to protect high-speed data interfaces from over-voltage caused by ESD (electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients). It has a typical capacitance of only 0.3pF (pin 1 to 2) making it suitable for use on circuits operating in excess of 3GHz without signal attenuation.

The SP0502BXTG is in a small SOT-523 package and each device can be configured to protect 1 bidirectional line or two unidirectional lines. The combination of small size, ultra-low capacitance, and high level of ESD protection makes it an ideal solution for applications such as HDMI, USB, MDDI, antennas, and DisplayPort.

### Functional Block Diagram and Pinout



Life Support Note:

**Not Intended for Use in Life Support or Life Saving Applications**

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

### Features

- RoHS compliant and lead-free
- ESD protection of  $\pm 15\text{kV}$  contact discharge,  $\pm 20\text{kV}$  air discharge, (IEC 61000-4-2)
- EFT, IEC 61000-4-4, 40A (5/50ns)
- Lightning protection, IEC 61000-4-5 2nd edition, 2A ( $t_p = 8/20\mu\text{s}$ )
- Stand-off voltage of 5V
- Low capacitance of 1pF @  $V_R = 0\text{V}$  (MAX)
- Low leakage current of 0.5 $\mu\text{A}$  at 5V (MAX)
- Small form factor (SOT523) and low profile (<1mm)
- No insertion loss to >3.0GHz
- AEC-Q101 qualified

### Additional Information



Datasheet



Resources



Samples

### Applications

- High-Definition Multimedia Interface (HDMI)
- Mobile Display Digital Interface (MDDI)
- RF/Antenna Circuits
- USB 2.0
- DisplayPort
- Mobile - Smartphone, Tablet, Notebook

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$P_{PK}$	Peak Pulse Power ( $t_p=8/20\mu s$ )	25	W
$I_{PP}$	Peak Pulse Current ( $t_p=8/20\mu s$ )	2	A
$T_{OP}$	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Thermal Information

Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

### Electrical Characteristics ( $T_{OP} = 25^\circ C$ )

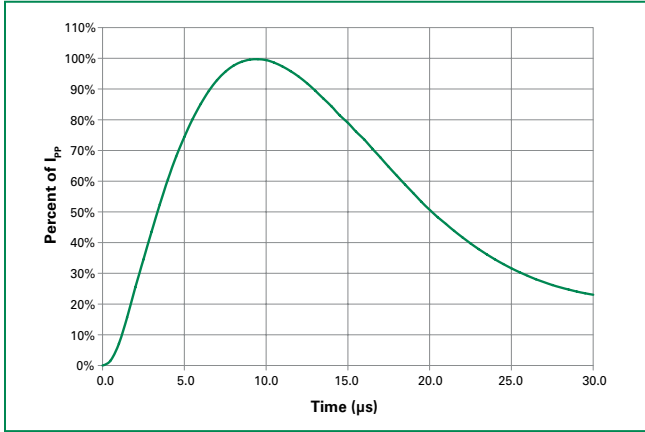
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$	$I_R \leq 1\mu A$ , Pin1 or Pin2 to Pin3 and Pin1 to Pin2			5.0	V
Reverse Breakdown Voltage	$V_{BR}$	$I_t = 1mA$ , Pin1 or Pin2 to Pin3	6			V
Leakage Current	$I_{LEAK}$	$V_R = 5V$			0.5	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP} = 1A$ , $t_p = 8/20\mu s$ , Pin 1 to Pin 2			12	V
Dynamic Resistance <sup>2</sup>	$R_{DYN}$	TLP, $t_p = 100ns$ , I/O to GND		0.45		$\Omega$
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact Discharge)	$\pm 15$			kV
		IEC 61000-4-2 (Air Discharge)	$\pm 20$			kV
Diode Capacitance <sup>1</sup>	$C_{I/O-I/O}$	Reverse Bias=0V, f=1MHz; Pin 1 to Pin2		0.25	0.5	pF
	$C_{I/O-GND}$	Reverse Bias=0V, f=1MHz; Pin 1 or Pin2 to Pin 3			1.0	pF

Note:

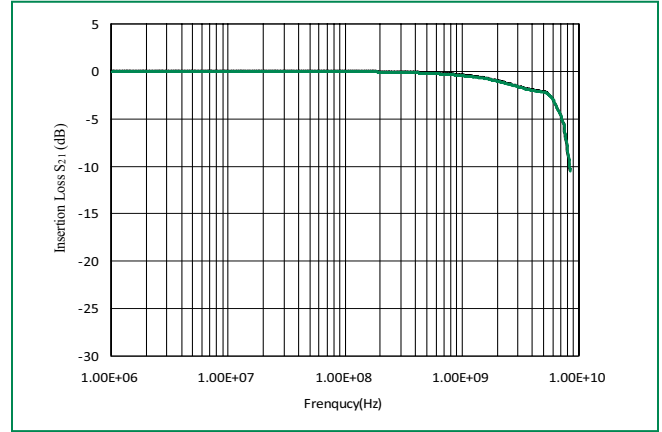
1 Parameter is guaranteed by design and/or device characterization.

2 Transmission Line Pulse (TLP) with 100ns width and 200ps rise time.

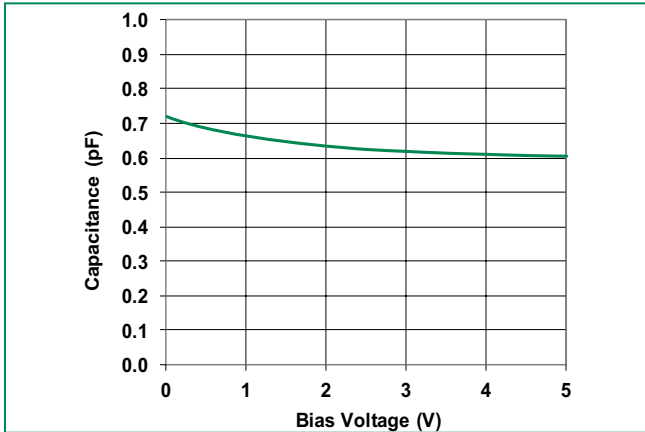
**Pulse Waveform**



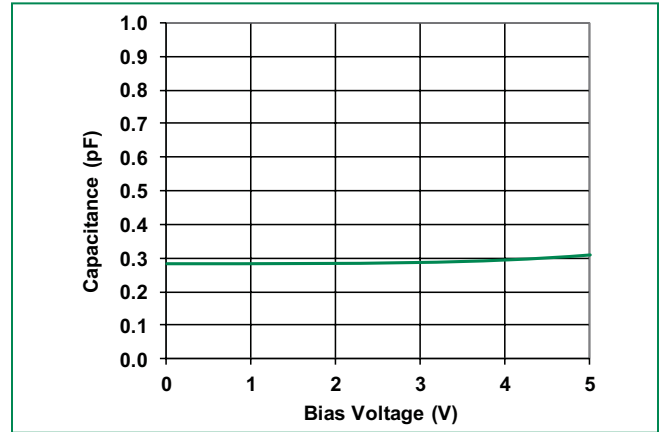
**Insertion Loss of Pin 1 to Pin 2 (I/O to I/O)**



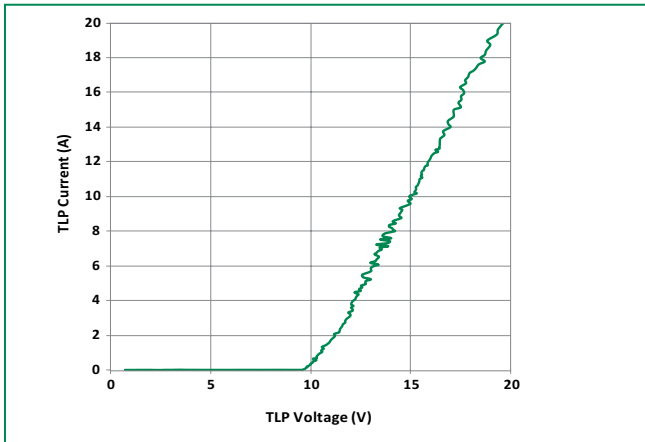
**Capacitance vs. Reverse Bias (Pin 1 or Pin 2 to Pin 3)**



**Capacitance vs. Reverse Bias (I/O-I/O) (Pin 1 to Pin 2)**



**Transmission Line Pulse (TLP)**



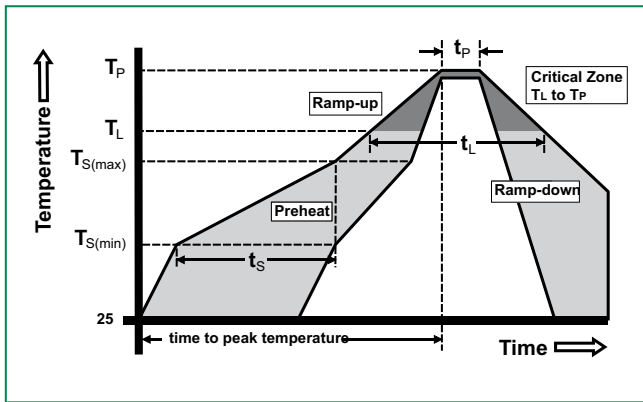


**Product Characteristics**

<b>Lead Plating</b>	Pre-Plated Frame
<b>Lead Material</b>	Copper Alloy
<b>Lead Coplanarity</b>	0.0004 inches (0.102mm)
<b>Substrate material</b>	Silicon
<b>Body Material</b>	Molded Epoxy
<b>Flammability</b>	UL 94 V-0

Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.



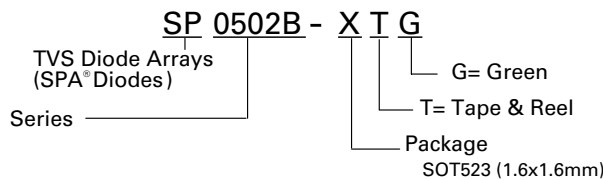
**Soldering Parameters**

Reflow Condition	Pb – Free assembly	
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak	3°C/second max	
$T_{S(max)}$ to $T_L$ - Ramp-up Rate	3°C/second max	
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_P$ )	260 <sup>+0/-5</sup> °C	
Time within 5°C of actual peak Temperature ( $t_p$ )	20 – 40 seconds	
Ramp-down Rate	6°C/second max	
Time 25°C to peak Temperature ( $T_P$ )	8 minutes Max.	
Do not exceed	260°C	

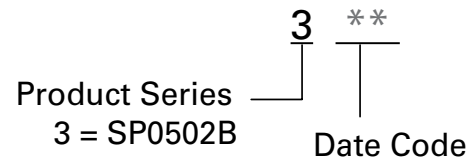
**Ordering Information**

Part Number	Package	Size	Marking	Min. Order Qty.
SP0502BXTG	SOT523	1.6x1.6mm	3**	3000

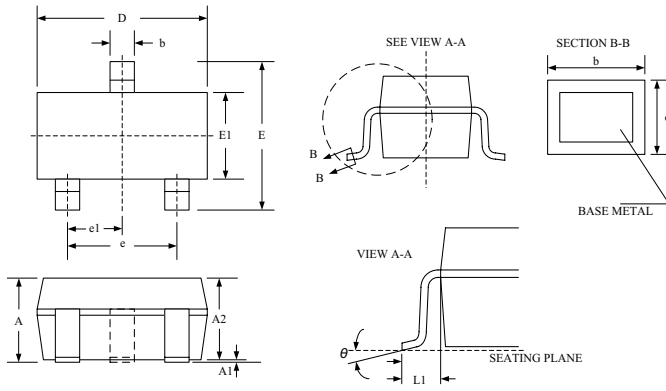
**Part Numbering System**



**Part Marking System**

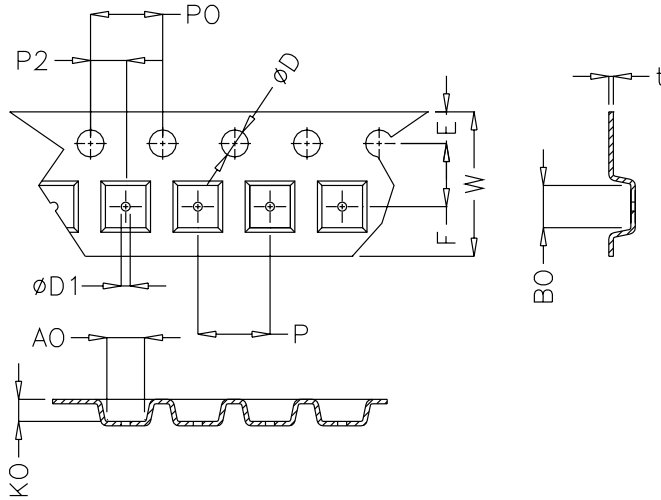


**Package Dimensions – SOT523**



	Millimetres			Inches		
	Min	Typ	Max	Min	Typ	Max
<b>A</b>	0.60	-	0.90	0.023	-	0.035
<b>A1</b>	0.00	-	0.10	0.000	-	0.004
<b>A2</b>	0.60	0.75	0.80	0.023	0.030	0.031
<b>b</b>	0.15	-	0.30	0.005	-	0.012
<b>c</b>	0.10	-	0.20	0.003	-	0.008
<b>D</b>	1.50	1.60	1.70	0.059	0.063	0.067
<b>e</b>	1.00 BSC			0.039 BSC		
<b>e1</b>	0.50 BSC			0.020 BSC		
<b>E</b>	1.45	1.60	1.75	0.057	0.063	0.069
<b>E1</b>	0.75	0.80	0.85	0.029	0.031	0.033
<b>L1</b>	0.22 REF			0.009 RFE		
<b>θ</b>	0°	-	8°	0°	-	8°

**Embossed Carrier Tape & Reel Specification – SOT523**



	Millimetres		Inches	
	Min	Max	Min	Max
<b>E</b>	1.65	1.85	0.065	0.073
<b>F</b>	3.45	3.55	0.135	0.139
<b>P2</b>	1.95	2.05	0.077	0.081
<b>D</b>	1.40	1.60	0.055	0.063
<b>D1</b>	0.45	0.55	0.017	0.021
<b>P0</b>	3.90	4.10	0.154	0.161
<b>10P0</b>	40.0+/- 0.20		1.574+/-0.008	
<b>W</b>	7.70	8.10	0.303	0.318
<b>P</b>	3.90	4.10	0.153	0.161
<b>A0</b>	1.73	1.83	0.068	0.072
<b>B0</b>	1.73	1.83	0.068	0.072
<b>K0</b>	0.64	0.74	0.025	0.029
<b>t</b>	0.22 max		0.009 max	